

CLAIMS

WHAT IS CLAIMED IS:

1. A manipulator configured to transfer a wafer comprising a finger structure and a plurality of support members, wherein the plurality of the support members are arranged at the finger structure and distributed at intervals on a same circumference, each support member being configured to contact an edge of the wafer to support the wafer to prevent the wafer from contacting the finger structure;

wherein each support member includes a support surface for supporting the wafer, the support surface being an inclined surface inclined relative to a horizontal plane, and a height of the inclined surface relative to the horizontal plane gradually increasing in a radial direction of the circumference along a direction away from a center of the circumference.

2. The manipulator according to claim 1, wherein the inclined surface is a plane and has an angle with the horizontal plane ranging from 1° to 60° .

3. The manipulator according to claim 2, wherein the angle is 5.75° .

4. The manipulator according to any one of claims 1 to 3, wherein each support member includes a support body and an anti-slip flexible member arranged at the support body, the support surface being formed at the anti-slip flexible member.

5. The manipulator according to claim 4, wherein the anti-slip flexible member is annular, and a cross-section shape of the anti-slip flexible member satisfies a point contact between the support surface and the wafer.

6. The manipulator according to claim 4, wherein an installation groove is formed at the support body, a part of the anti-slip flexible member is arranged inside the installation groove, and another part is arranged outside the installation groove.

7. The manipulator according to any one of claims 1 to 3, wherein at least one marking line is provided on the support surface of each supporting member, and each marking line is used to indicate a position of the edge of the wafer of a size on the support surface.

8. The manipulator according to claim 1, wherein the finger structure includes two fingers arranged at an interval in a direction parallel to the horizontal plane, and the interval between the two fingers is set to prevent the wafer from contacting the fingers.

9. The manipulator according to claim 1, further comprising a positioning member and a fastener, wherein the positioning member is arranged at the finger structure and configured to limit a position of the support member at the finger structure, and the fastener is configured to fixedly connect the support member to the finger structure.